



Material Content Data Sheet



Sales Product Name		TLE6711G		Issued		1. August 2018		
MA#		MA001731838						
Package		PG-DSO-14-1		Weight*		143.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.251	4.34	4.34	43418	43418
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		419	
	non noble metal	iron	7439-89-6	1.207	0.84		8383	
wire	non noble metal	copper	7440-50-8	49.007	34.04	34.93	340392	349299
	noble metal	gold	7440-57-5	0.340	0.24	0.24	2361	2361
	encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1148
plastics		epoxy resin	-	7.605	5.28		52824	
	inorganic material	silicondioxide	60676-86-0	74.895	52.02	57.41	520204	574176
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8517	8517
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7153	7153
glue	plastics	acrylic resin	-	0.478	0.33		3317	
	noble metal	silver	7440-22-4	1.693	1.18	1.51	11759	15076
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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